2. Specification

2-1. GSM General Specification

	GSM850	EGSM 900	DCS1800	PCS1900	WCDMA 2100	WCDMA 1900	WCDMA 900	WCMDA 850
Freq. Band[MHz] Uplink/ Downlink	824~849 869~894	880~915 925~960	1710~1785 1805~1880	1850~1910 1930~1990	1920~1980 2110~2170	1852~1907 1932~1987	880~915 925~960	824~849 869~894
ARFCN range	128~251	0~124 & 975~1023	512~885	512~810	UL: 9612~9888 DL: 10562~10838	UL: 9262~9538 DL: 9662~9938	UL: 2712~2863 DL: 2937~3088	UL: 4132~4233 DL: 4357~4458
Tx/Rx spacing	45MHz	45MHz	95MHz	80MHz	190MHz	80MHz	45MHz	45MHz
Mod. Bit rate/ Bit Period	270.833kbps 3.692us	270.833kbps 3.692us	270.833kbps 3.692us	270.833kbps 3.692us	3.84Mcps	3.84Mcps	3.84Mcps	3.84Mcps
Time Slot Period/ Frame Period	576.9us 4.615ms	576.9us 4.615ms	576.9us 4.615ms	576.9us 4.615ms	FrameLength: 10ms Slotlength: 0.667ms	FrameLength: 10ms Slotlength: 0.667ms	FrameLength: 10ms Slotlength: 0.667ms	FrameLength: 10ms Slotlength: 0.667ms
Modulation	0.3GMSK	0.3GMSK	0.3GMSK	0.3GMSK	QPSKHQPSK	QPSKHQPSK	QPSKHQPSK	QPSKHQPSK
MS Power	33dBm~5dBm	33dBm~5dBm	30dBm~0dBm	30dBm~0dBm	24dBm~ -50dBm	24dBm~ -50dBm	24dBm~ -50dBm	24dBm~ -50dBm
Power Class	5pcl ~ 19pcl	5pcl ~ 19pcl	Opcl ~ 15pcl	Opcl ~ 15pcl	3(max+24dBm)	3(max+24dBm)	3(max+24dBm)	3(max+24dBm)
Sensitivity	-102dBm	-102dBm	-100dBm	-100dBm	-106.7dBm	-106.7dBm	-106.7dBm	-106.7dBm
TDMA Mux	8	8	8	8	8	8	8	8
Cell Radius	35Km	35Km	2Km	2Km	2Km	2Km	2Km	2Km

2-2. GSM Tx Power Class

TX Power control level	GSM850	TX Power control level	EGSM900	TX Power control level	DCS1800	TX Power control level	PCS1900
5	33±2 dBm	5	33±2 dBm	0	30±3 dBm	0	30±3 dBm
6	31±2 dBm	6	31±2 dBm	1	28±3 dBm	1	28±3 dBm
7	29±2 dBm	7	29±2 dBm	2	26±3 dBm	2	26±3 dBm
8	27±2 dBm	8	27±2 dBm	3	24±3 dBm	3	24±3 dBm
9	25±2 dBm	9	25±2 dBm	4	22±3 dBm	4	22±3 dBm
10	23±2 dBm	10	23±2 dBm	5	20±3 dBm	5	20±3 dBm
11	21±2 dBm	11	21±2 dBm	6	18±3 dBm	6	18±3 dBm
12	19±2 dBm	12	19±2 dBm	7	16±3 dBm	7	16±3 dBm
13	17±2 dBm	13	17±2 dBm	8	14±3 dBm	8	14±3 dBm
14	15±2 dBm	14	15±2 dBm	9	12±4 dBm	9	12±4 dBm
15	13±2 dBm	15	13±2 dBm	10	10±4 dBm	10	10±4 dBm
16	11±3 dBm	16	11±3 dBm	11	8±4 dBm	11	8±4 dBm
17	9±3dBm	17	9±3dBm	12	6±4 dBm	12	6±4 dBm
18	7±3 dBm	18	7±3 dBm	13	4±4 dBm	13	4±4 dBm
19	5±3 dBm	19	5±3 dBm	14	2±5 dBm	14	2±5 dBm
				15	0±5 dBm	15	0±5 dBm

3. Operation Instruction and Installation

Main Function

- Android OS: Kitkat (4.4.4)
- SC7727S Dual Core 1.2 GHz Processor
- 100.8 mm 4" TFT LCD(480x800, WVGA)
- 1500 mAh Battery
- CMOS 5MP AF Flash + VGA Camera
- 4G Bytes (eMMC) + 512M Bytes (DDR2)
- HSPA+ 21.1Mbps(900/2100 MHz)
- A-GPS / BT v4.0 / USB v2.0 / WiFi (802.11 b/g/n 2.4GHz)
- · Sensors: Accelerometer
- · Additional:
- TouchWiz 4.0 UX
- Wi-Fi Direct
- · Dual Sim

9. Reference Abbreviate

Reference Abbreviate

AAC: Advanced Audio Coding.AVC: Advanced Video Coding.

- BER: Bit Error Rate

- BPSK: Binary Phase Shift Keying

- CA : Conditional Access

- CDM: Code Division Multiplexing

- C/I: Carrier to Interference

- DMB : Digital Multimedia Broadcasting

EN : European StandardES : Elementary Stream

- ETSI: European Telecommunications Standards Institute

MPEG: Moving Picture Experts Group

- PN : Pseudo-random Noise

- PS : Pilot Symbol

- QPSK: Quadrature Phase Shift Keying

RS : Reed-SolomonSI : Service Information

- TDM: Time Division Multiplexing

- TS: Transport Stream

1. Safety Precautions

1-1. Repair Precaution

Before attempting any repair or detailed tuning, shield the device from RF noise or static electricity discharges.

Use only demagnetized tools that are specifically designed for small electronic repairs, as most electronic parts are sensitive to electromagnetic forces.

Use only high quality screwdrivers when servicing products. Low quality screwdrivers can easily damage the heads of screws.

Use only conductor wire of the properly gauge and insulation for low resistance, because of the low margin of error of most testing equipment.

We recommend 22-gauge twisted copper wire.

Hand-soldering is not recommended, because printed circuit boards (PCBs) can be easily damaged, even with relatively low heat. Never use a soldering iron with a power rating of more than 100 watts and use only lead-free solder with a melting point below 250°C (482°F).

Prior to disassembling the battery charger for repair, ensure that the AC power is disconnected. Always use the replacement parts that are registered in the SEC system. Third-party replacement parts may not function properly.

1-2. ESD(Electrostatically Sensitive Devices) Precaution

Many semiconductors and ESDs in electronic devices are particularly sensitive to static discharge and can be easily damaged by it. We recommend protecting these components with conductive anti-static bags when you store or transport them.

Always use an anti-static strap or wristband and remove electrostatic buildup or dissipate static electricity from your body before repairing ESDs.

Ensure that soldering irons have AC adapter with ground wires and that the ground wires are properly connected.

Use only desoldering tools with plastic tips to prevent static discharge.

Properly shield the work environment from accidental electrostatic discharge before opening packages containing ESDs.

The potential for static electricity discharge may be increased in low humidity environments, such as air-conditioned rooms. Increase the airflow to the working area to decrease the chance of accidental static electricity discharges.

6. Level 1 Repair

6-1. S/W installation

6-1-1. Required items in order to install S/W

- Installation program: Downloader Program (Odin3 v3.09.exe)
- SM-G316HU/DS Mobile Phone
- Data Cable
- JIG BOX GH91-11888A
- JIG Cable GH81-10623A
- Adapter GH81-11888K
- Serial Cable
- Mobile device specific S/W: Binary files

*** Settings**



Connect ANYWAY JIG BOX with JIG CABLE (Phone to JIG) or PC to Phone Using Data Cable





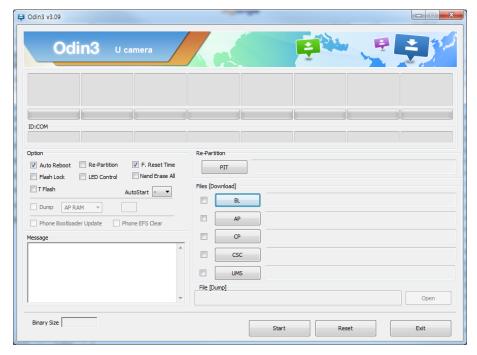
Chipset Solution Switch: 2



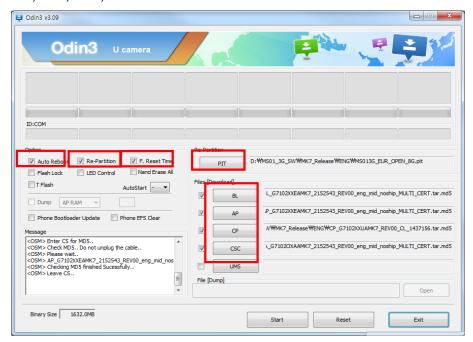


No.	Soluti on
1	Agere TC
2	HP, Vision, Infineon
3	NXP Sysol
4	NXP Swift Broadcom
5	UMTS (Qualcom)
6	EMP

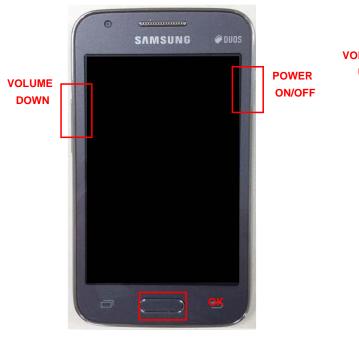
- 6-1-2. S/W Installation Program (Downloader program)
 - Open up the S/W Installation Program by executing the "Odin3 v3.09.exe" ("odin3.ini" file should be in the same folder with odin3 v3.09.exe)



- 1. Enable the check mark by click on the following options,
 - Check Auto Reboot, and F. Reset Time
 - Check BL, AP, CP, and CSC Files



- 2. Enter into Download Mode
- 1. Press Volume Down button, OK button, and ON/OFF Button simultaneously.
- 2. After confirm the warning message, Volume UP button press to enter download mode.





3. Connect the device to PC via Data Cable. Make sure that the one of communication port [ID:COM] box is pop-up. The device is now connected with the PC and ready to download the binary file into the device.



4. Start downloading binary file into the device by clicking Start Button on the screen. the green colored "PASS!" sign will appear on the upper-left box if the binary file has been successfully downloaded into the device.



- 5. Disconnect the device from the Data cable.
- Once the device boots up, you can check the version of the binary file or name by pressing the following code in sequence;
 *#1234#

Full Reset:

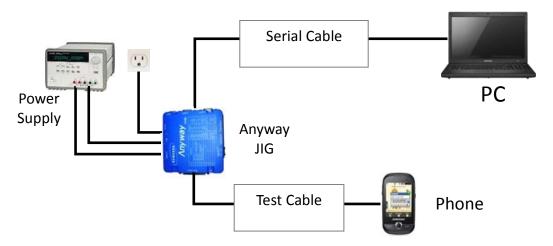
Apps > Settings > Backup and reset > Factory data reset

6-2 IMEI writing

6-2-1 Preparation

- New IMEI writing Program has been released.
- Supported Model: Models which CAB files are uploaded on HHPsvc INI File category, instead of ini file.
- Refer to below IMEI writing procedure.

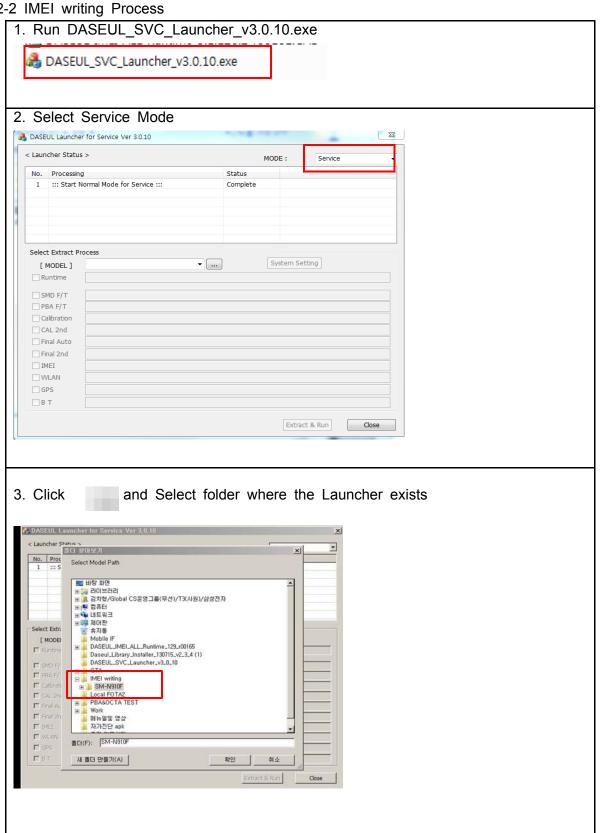
- H/W



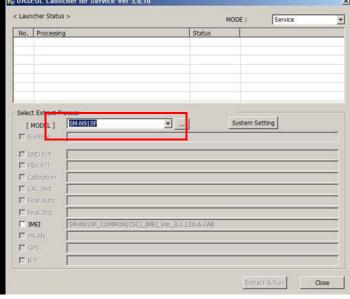
- S/W

O/ 11					
① Library Install To use Daseul, library files should be installed.					
	Refer to SVC Bulletin				
	"(11-82) Daseul (New IMEI writing Program) Library Install gui				
	de_rev1.0"				
②Launcher DASEUL_SVC_Launcher_v3_0_10 or higher					
	-Uploaded on HHPsvc Notice				
3 Runtime File	1. DASEUL_IMEI_ALL_Runtime_129_r00165 .CAB or higher				
	-Uploaded on HHPsvc Notice				
	2. Make 'ModelName' folder at the same position with				
	launcher & Runtime file.				
	SM-G316HU				
	DASEUL_IMEI_ALL_Runtime_3, 1, 129, 0,				
	B DASEUL_SVC_Launcher_v3, 0, 10, exe B DASEUL_SVC_LAUNCHER_V3, 0, ex				
4 Model File	Copy Model File under the 'Model Name' folder				

6-2-2 IMEI writing Process

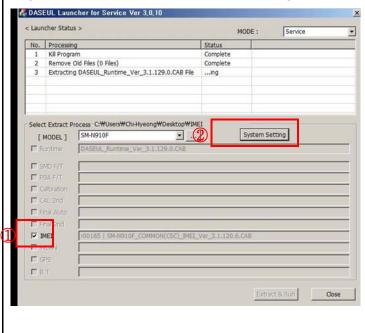


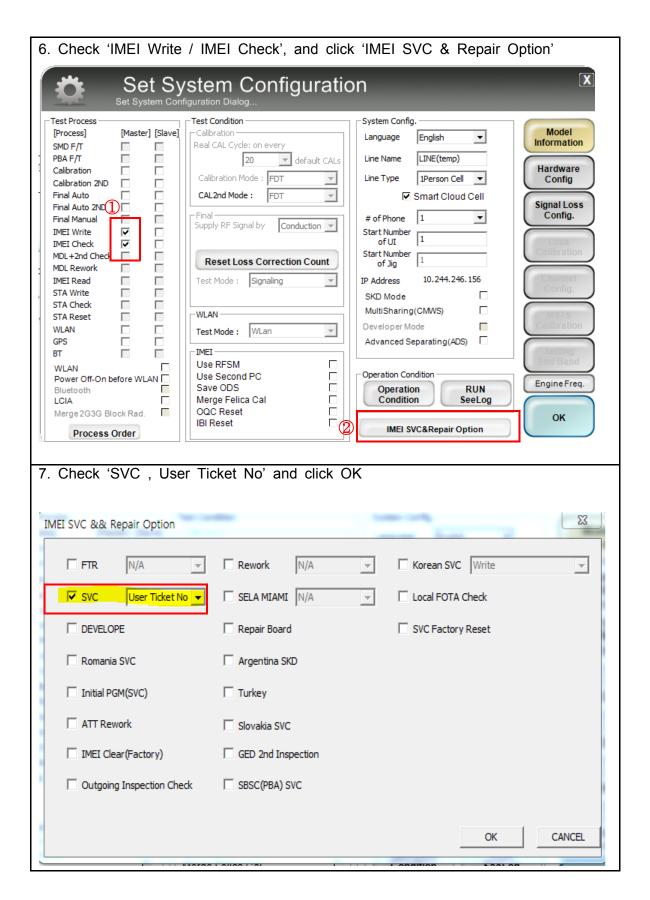


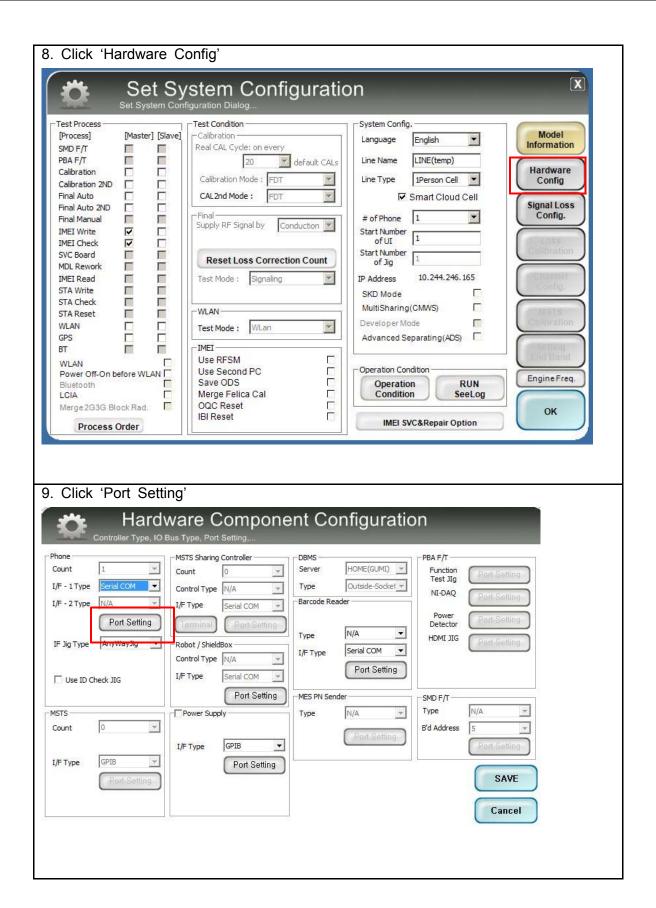


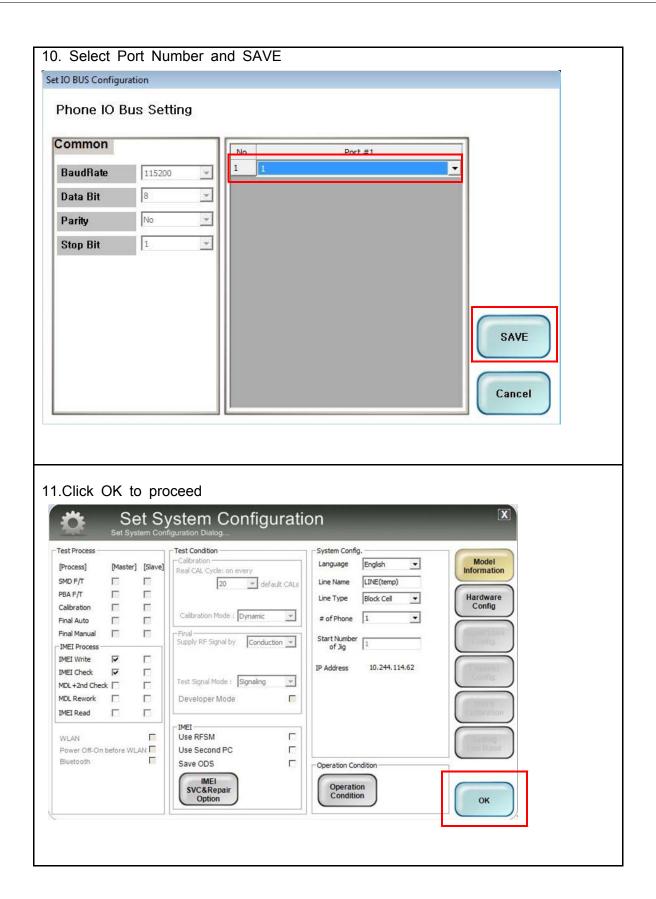
5. Check IMEI and click 'System Setting'

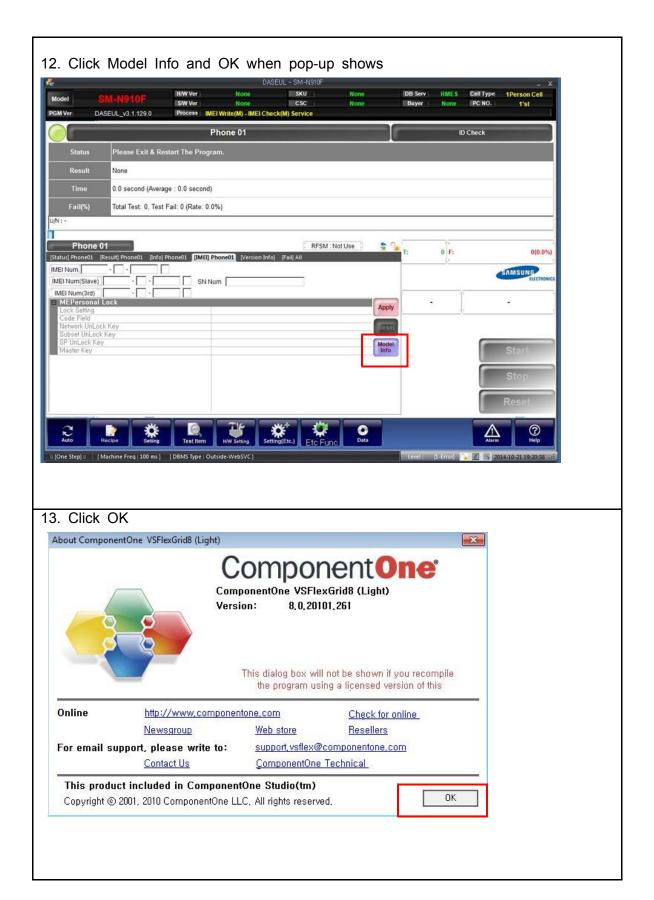
**Once you setup the setting, you don't have to do it again, unless there is ch ange. From second run of the IMEI program, check IMEI and click 'Extract & Run'.



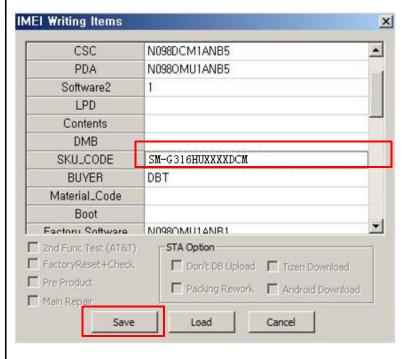




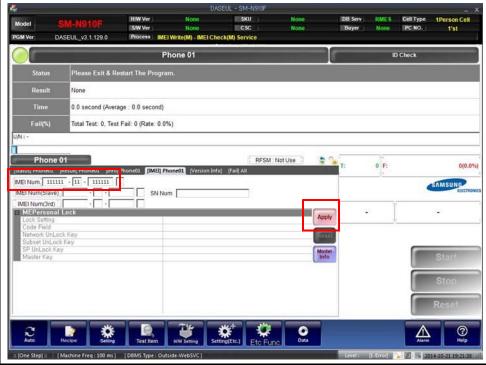




- 14. Input SKU_CODE and BUYER, then click Save button.
- ※ Refer to HHPsvc→IMEI Review to check SKU Code and buyer



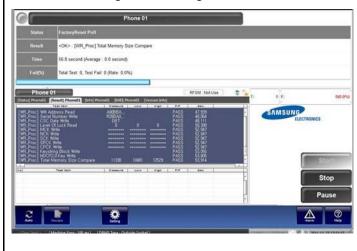
15. Input IMEI Number and click Apply



16. (1) Click Start, and input IMEI writing ID and Password → 2 input Ticket No



- 17. Connect the phone to Anyway JIG
- When you connect the phone, the phone should be turned off.
 After connecting the phone, the phone will be booted automatically.
- 18. IMEI Writing Proceeding





6-3. Boot Recovery

6-3-1. Symptom

No Power on, Unable to enter download mode.

6-3-2. Coverage

The device which get damaged for bootloader.

6-3-3. Required items in order to do Boot Recovery

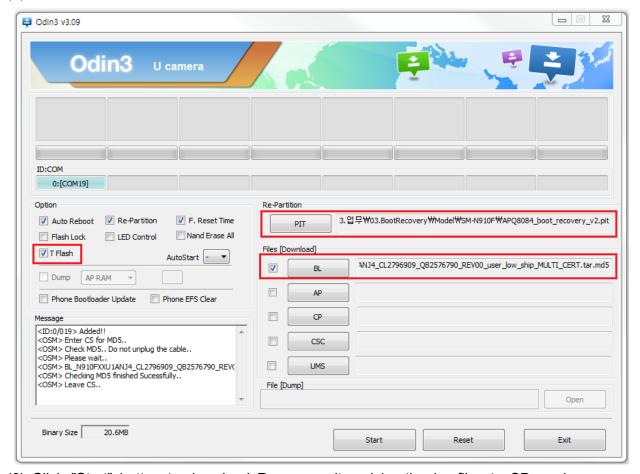
- Downloader Program (Odin3 v3.09.3.exe)
- SM-G316HU Mobile Phone(Normal device)
- Data Cable (GH39-01661A)
- Micro SD Card (Higher than SDHC type and 4GB)
- Full S/W binary(pit, BL, AP, CP)
- · Recovery pit file and bootloader
 - pit file: APQ8084_boot_recovery_v2.pit
 - boot loader: normal bootloader(BL)

6-3-4. Brief process for Boot Recovery

- 1. Download recovery pit and bootloader to SD card by using normal device
- 2. Insert SD card to no power device and try to enter download mode.
- 3. Download full S/W to the defected device

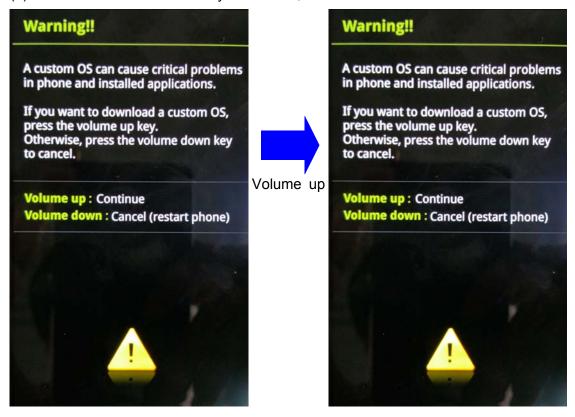
6-3-5. Process of Boot Recovery

- 1. SW download
- (1) Download full S/W(BL, AP, CP, CSC) to normal device.
- 2. Make SD card for Recovery
- (1) Run Odin3 v3.09.3 exe
- (2) Load "APQ8084_boot_recovery_v2.pit" in PIT tap and "normal bootloader file" in BL tap.
- (3) Check "T-Flash" option
- (4) Insert SD card to normal device and enter to download mode.
- (5) Connect the device to PC

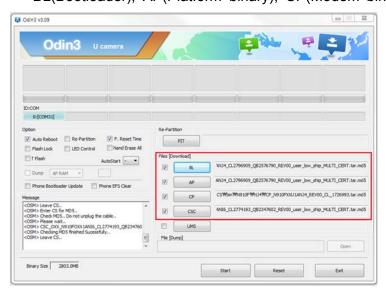


- (6) Click "Start" button to download Recovery pit and bootloader files to SD card.
 - If it is Pass, SD card has successfully made for boot recovery.
 - If it is Fail, try to this with another SD card.(It would be defect of SD card)

- 3. Boot Recovery for damaged device
- (1) Insert SD card to "No power" device
- (2) Enter to download mode, using key combination(Volume down + Home + Power)
- (3) If the device is successfully recovered, the device will enter download mode.



(4) After entering download mode, download full S/W to the device including BL(Bootloader), AP(Platform binary), CP(Modem binary) and CSC.



6-4. RF Calibration

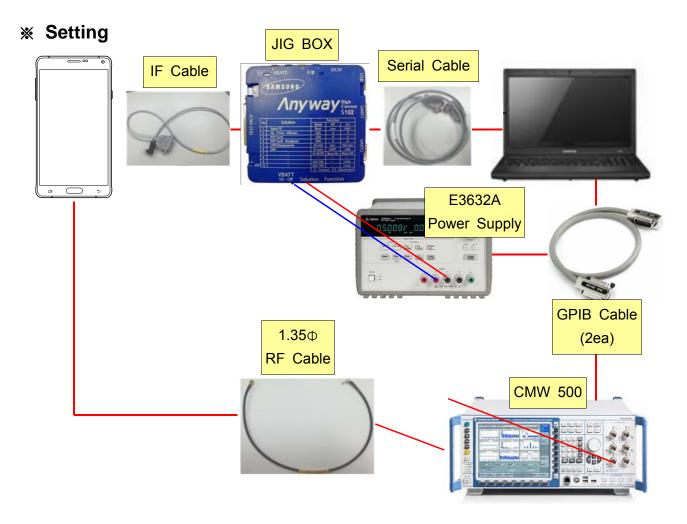
6-1-1. Required items in order to calibrate RF

- Installation program: RF Calibration Program
 - Daseul_Launcher_vx.x.xx.exe
 - Daseul_CAL_ALL_Runtime_x.x.xxx.x.CAB
 - Model File (SM-N910F_OPEN_CALIBRATION_VER_x.x.xxx.xxx.CAB)

* It is required to use the latest program.

- SM-G316HU Mobile Phone
- E3632A Power Supply
- JIG BOX (GH81-11888A)
- Adapter (GH81-11888K)
- 4 Port Divider (GH81-11962A)
- 1.35⊕ RF Cable (GH81-11962D, 2ea)

- R&S CMW500
- GPIB Cable (2ea)
- IF Cable (GH81-10631A)
- UART Serial Cable
- 50Ω Termination (GH81-11962E, 2ea)
- Divider RF Cable (GH81-11962B)



• Table of test cables

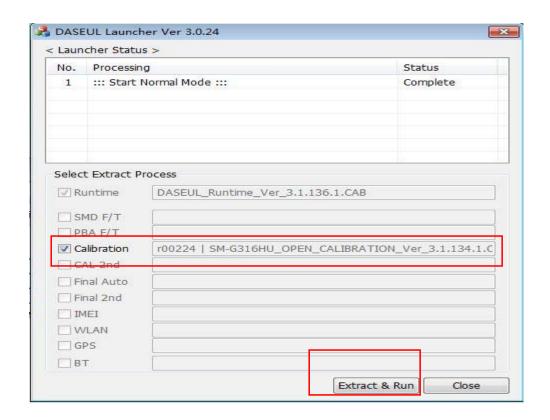
IF Cable	GH81-10631A	GH81-10952A	GH81-11171A	
ii Cable	11 pin	7 pin (New)	7 pin (Old)	
RF Cable	GH81-11962D	GH81-11962G	GH81-11962C	GH81-11962F
	1.35T, Short	1.35T, Long	1.6T, Short	1.6T, Long
4 Port Divider	GH81-11962A			
	Use / No use			

6-1-2. RF Calibration Program

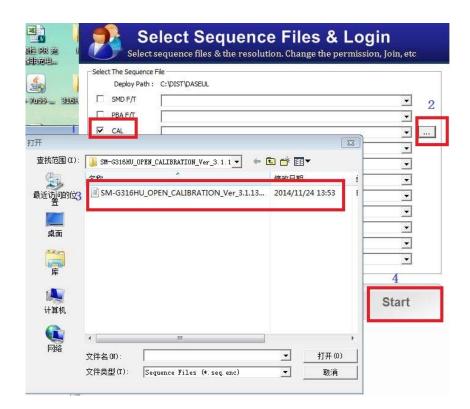
1. Run the RF Calibration Program Launcher, 'DASEUL_Launcher_vx.x.xx.exe'.

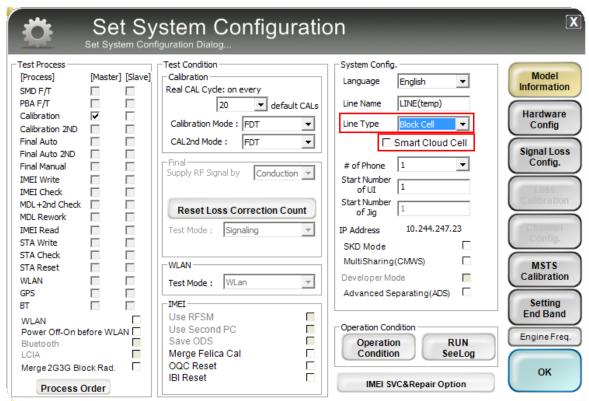


2. Check the 'Calibration' menu, and select 'Extract & Run'.



3. Check the 'CAL' and open the model file, then select 'Start' button.





4. Change the Line Type to 'Block Cell' and disable 'Smart Cloud Cell'.

 Set the GPIB address of MSTS(CMW500) and Power Supply(E3632A) to enter 'Hardware Config' and 'Save'. (Check the GPIB address of equipments in advance)

